

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$ max	I_D $T_C = +25^\circ C$
100V	80m Ω @ $V_{GS} = 10V$	17A
	99m Ω @ $V_{GS} = 6V$	15A

Description

This new generation complementary MOSFET features low on-resistance and fast switching, making it ideal for high efficiency power management applications.

Applications

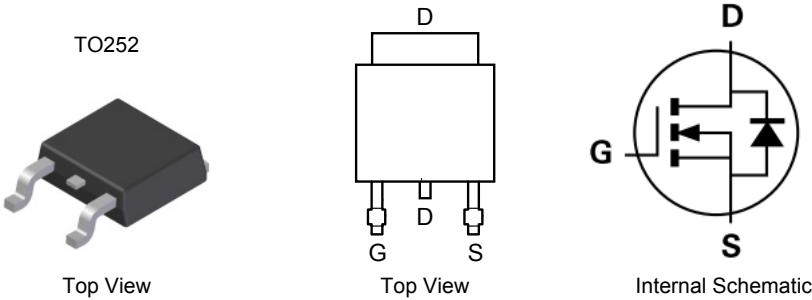
- Power Management Functions
- DC-DC Converters

Features

- Low $R_{DS(ON)}$ – ensures on state losses are minimized
- Small form factor thermally efficient package enables higher density end products
- Lead-Free Finish; RoHS compliant (Note 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**

Mechanical Data

- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish – Matte Tin annealed over Copper leadframe Solderable per MIL-STD-202, Method 208 **(E3)**
- Weight: 0.33 grams (approximate)



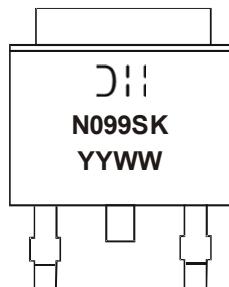
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN10H099SK3-13	TO252	2,500/Tape & Reel

Notes:

- EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



DII = Manufacturer's Marking
 N099SK = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Last Digit of Year (ex: 14 = 2014)
 WW = Week Code (01 to 53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V_{DSS}	100	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current (Note 5) $V_{GS} = 10\text{V}$	$T_C = +25^\circ\text{C}$ $T_C = +70^\circ\text{C}$	I_D	17 13
Pulsed Drain Current (10 μs pulse, duty cycle = 1%)	I_{DM}	20	A
Avalanche Current, $L = 1\text{mH}$	I_{AS}	7.5	A
Avalanche Energy, $L = 1\text{mH}$	E_{AS}	28.5	mJ

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P_D	34	W
		22	
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	51	°C/W
		3.6	
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	100	—	—	V	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(\text{th})}$	1.5	2	3	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	—	67	80	mΩ	$V_{GS} = 10\text{V}, I_D = 3.3\text{A}$
		—	69	99		$V_{GS} = 6\text{V}, I_D = 3\text{A}$
Diode Forward Voltage	V_{SD}	—	0.77	—	V	$V_{GS} = 0\text{V}, I_S = 3.2\text{A}$
DYNAMIC CHARACTERISTICS (Note 6)						
Input Capacitance	C_{iss}	—	1172	—	pF	$V_{DS} = 50\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Output Capacitance	C_{oss}	—	40.8	—		
Reverse Transfer Capacitance	C_{rss}	—	31.3	—	nC	$V_{DS} = 50\text{V}, I_D = 3.3\text{A}$
Gate Resistance	R_G	—	1.6	—		
Total Gate Charge ($V_{GS} = 10\text{V}$)	Q_g	—	25.2	—	nC	$V_{DS} = 50\text{V}, I_D = 3.3\text{A}$
Total Gate Charge ($V_{GS} = 4.5\text{V}$)	Q_g	—	12.2	—		
Gate-Source Charge	Q_{gs}	—	5.3	—	ns	$V_{DD} = 50\text{V}, R_G = 6.0\Omega, I_D = 3.3\text{A}$
Gate-Drain Charge	Q_{gd}	—	5.9	—		
Turn-On Delay Time	$t_{D(\text{on})}$	—	5.4	—	ns	$V_{DD} = 50\text{V}, R_G = 6.0\Omega, I_D = 3.3\text{A}$
Turn-On Rise Time	t_r	—	5.9	—		
Turn-Off Delay Time	$t_{D(\text{off})}$	—	20	—	ns	$I_F = 3.3\text{A}, dI/dt = 100\text{A}/\mu\text{s}$
Turn-Off Fall Time	t_f	—	7.3	—		
Body Diode Reverse Recovery Time	t_{rr}	—	19.7	—	nC	$I_F = 3.3\text{A}, dI/dt = 100\text{A}/\mu\text{s}$
Body Diode Reverse Recovery Charge	Q_{rr}	—	15.9	—		

Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

6. Guaranteed by design. Not subject to product testing.

7. Short duration pulse test used to minimize self-heating effect.

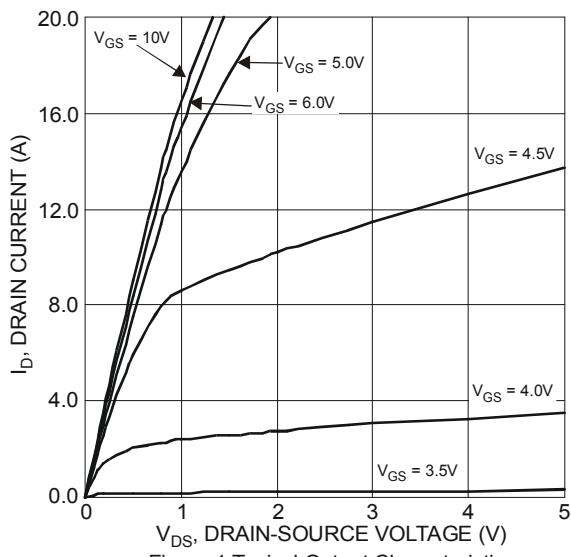


Figure 1 Typical Output Characteristics

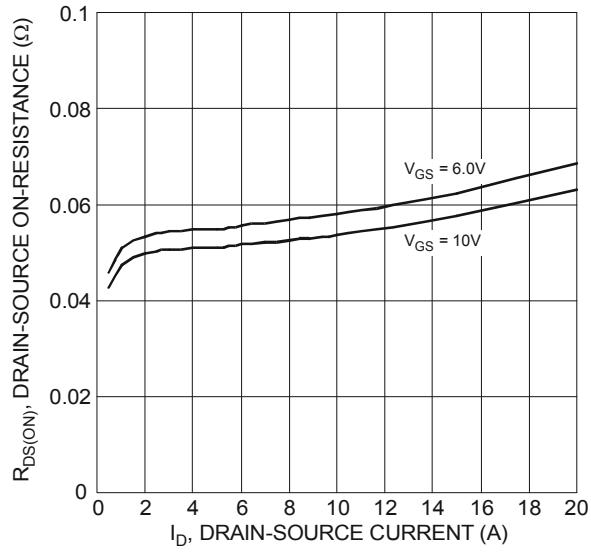
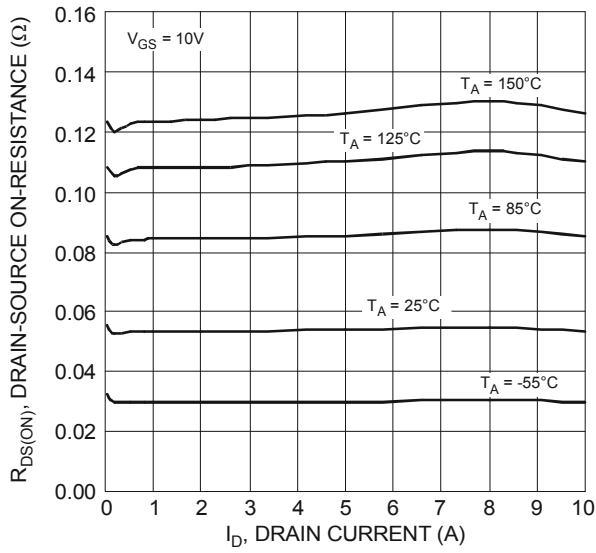
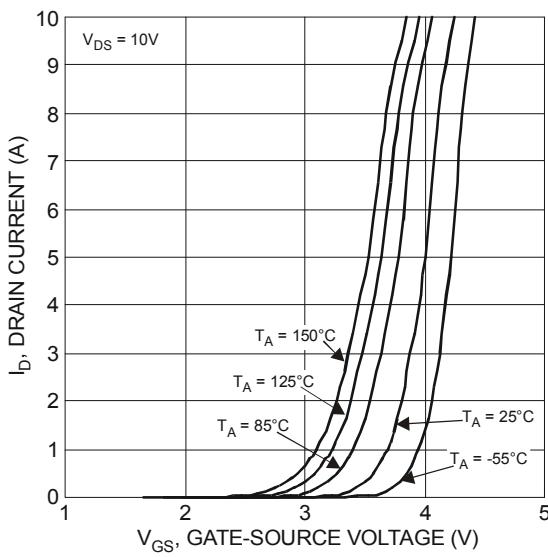
Figure 3 Typical On-Resistance vs.
Drain Current and Gate VoltageFigure 5 Typical On-Resistance vs.
Drain Current and Temperature

Figure 2 Typical Transfer Characteristics

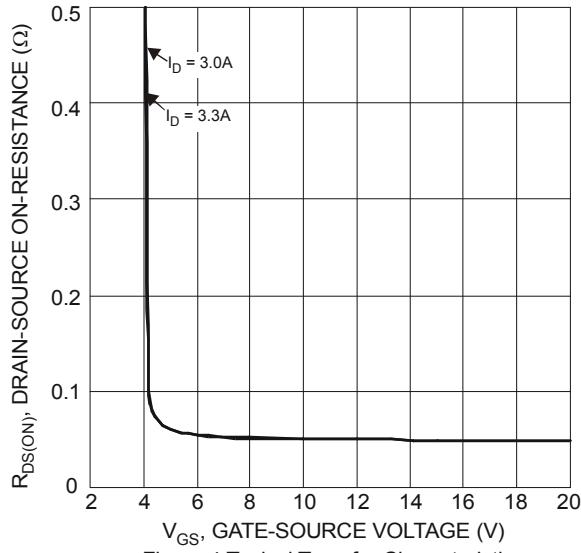


Figure 4 Typical Transfer Characteristics

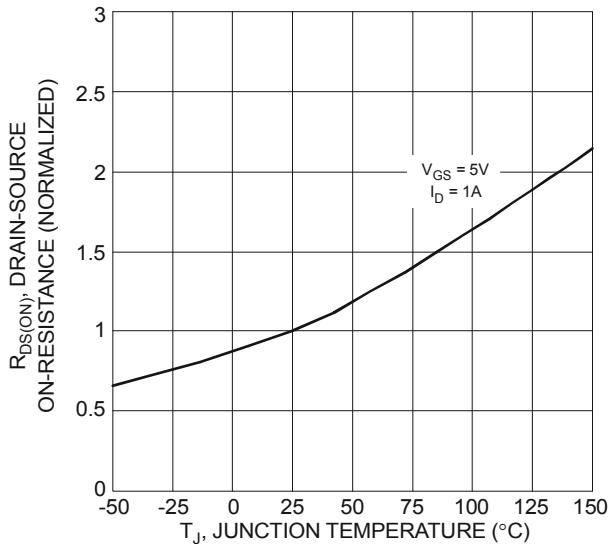
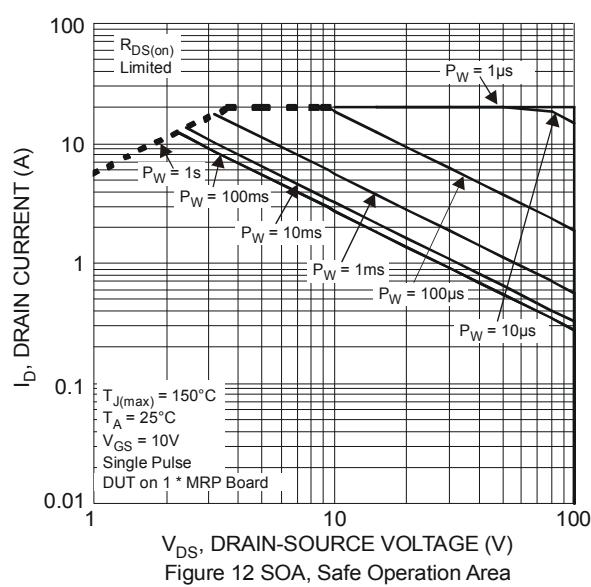
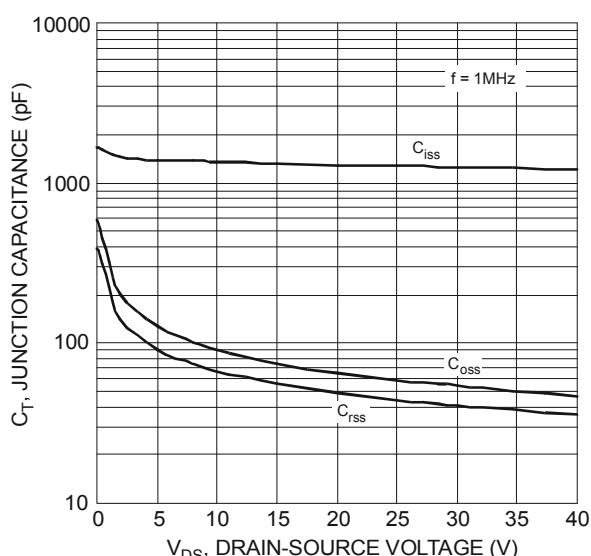
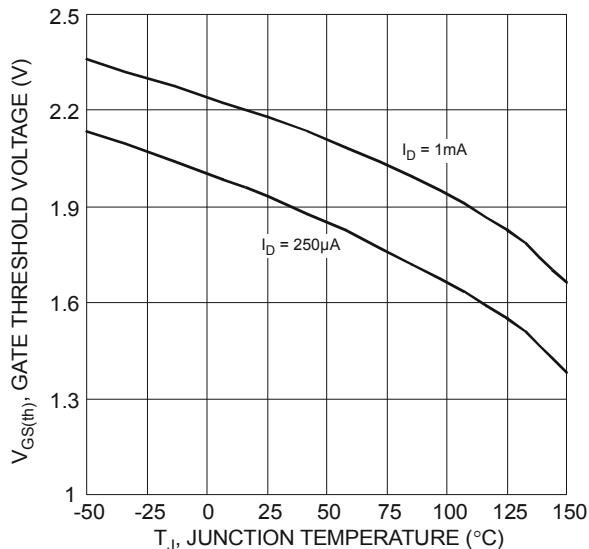
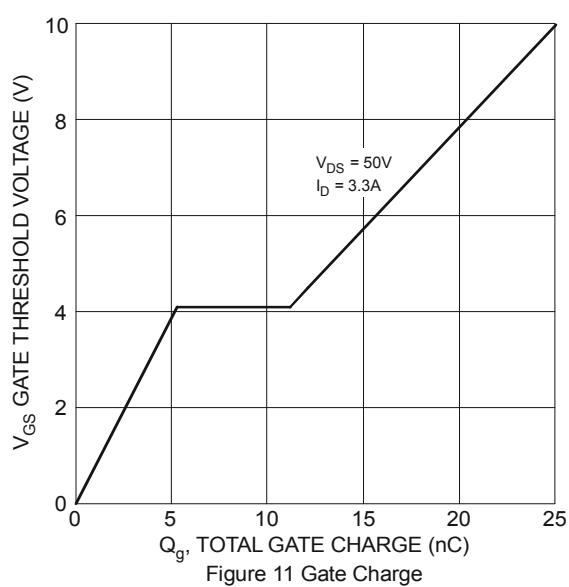
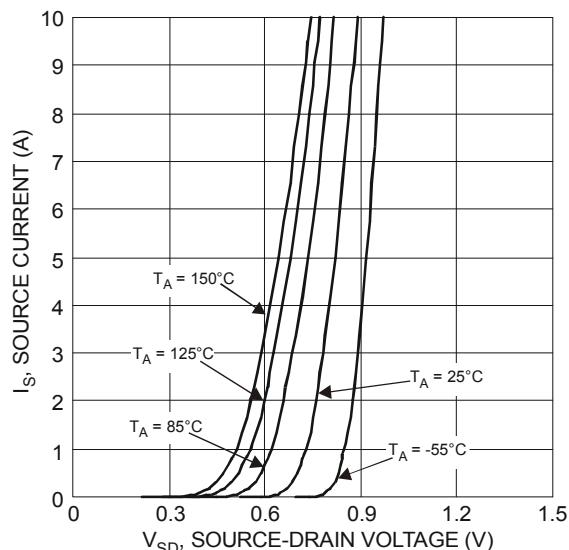
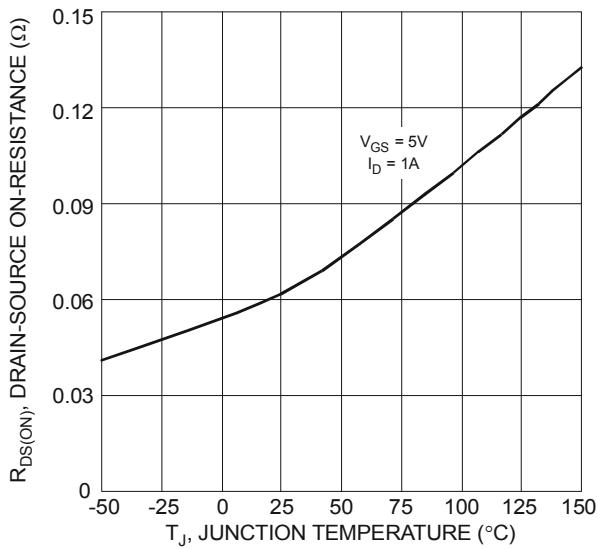


Figure 6 On-Resistance Variation with Temperature



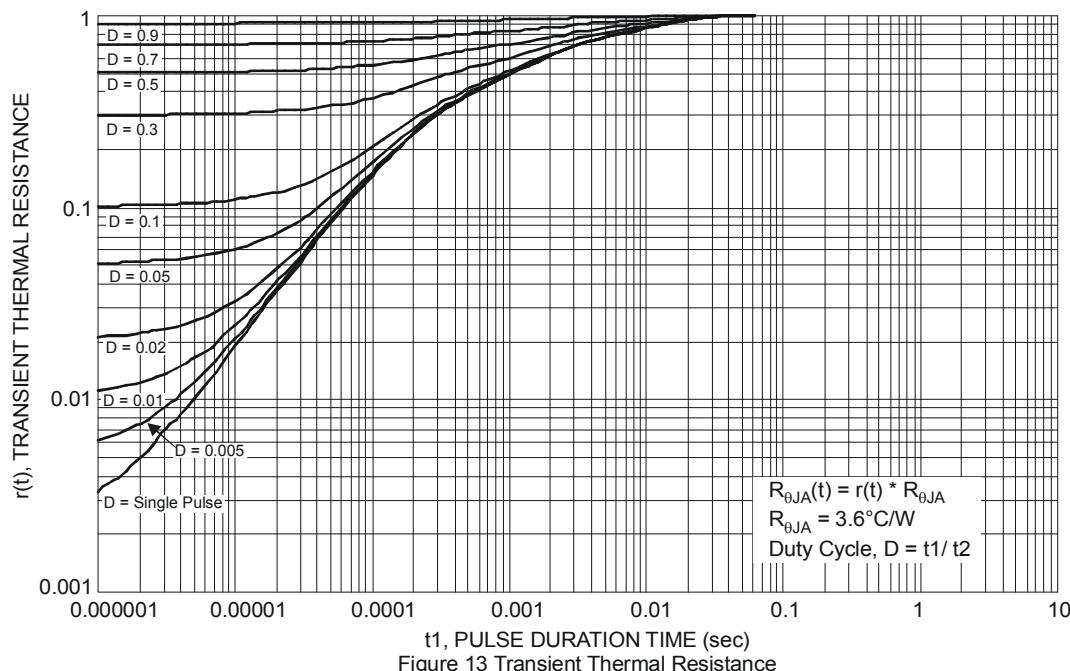
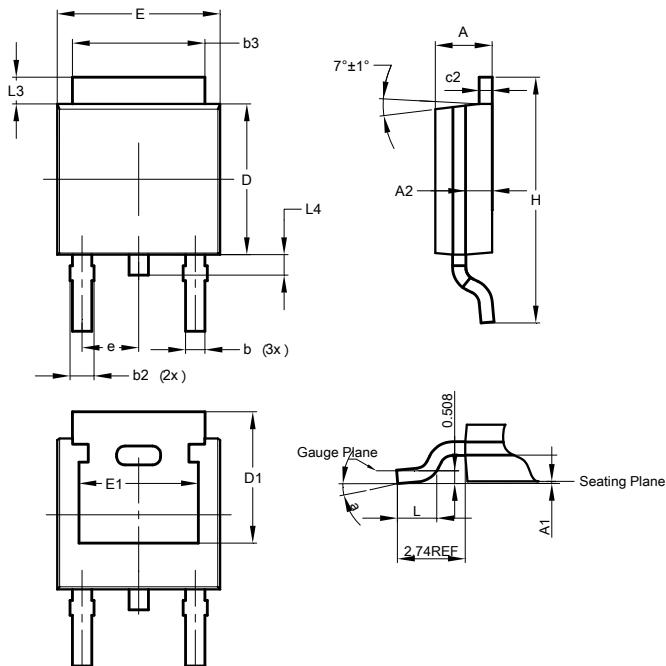


Figure 13 Transient Thermal Resistance

Package Outline Dimensions

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for latest version.

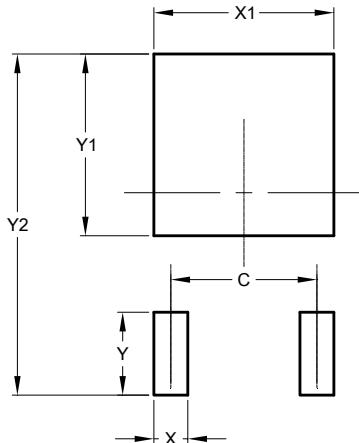


TO252 (DPAK)			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c2	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	-	-
e	-	-	2.286
E	6.45	6.70	6.58
E1	4.32	-	-
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	-

All Dimensions in mm

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	4.572
X	1.060
X1	5.632
Y	2.600
Y1	5.700
Y2	10.700

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